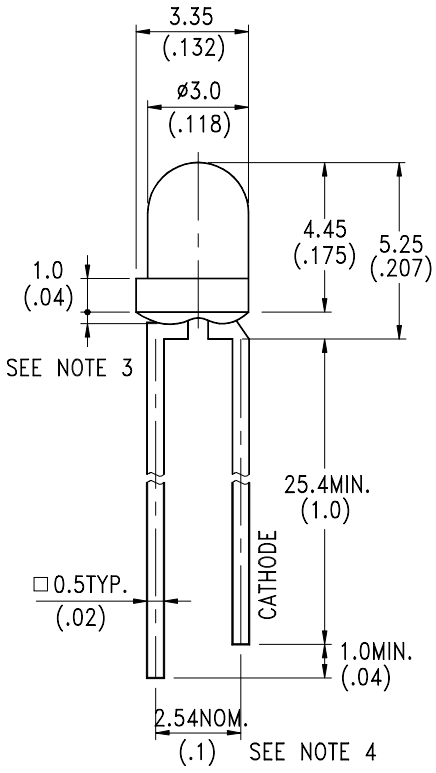
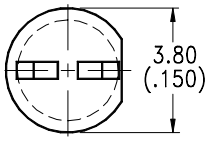
FEATURES

* SPECIAL FOR HIGH CURRENT AND LOW FORWARD VOLTAGE
* LOW COST MINIATURE PLASTIC END LOOKING PACKAGE
* WIDE VIEWING ANGLE
* CLEAR TRANSPARENT COLOR PACKAGE

PACKAGE DIMENSIONS





BOTTOM VIEW

NOTES:
1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25mm(.010") unless otherwise noted.
3. Protruded resin under flange is 1.5mm(.059") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice for performance improvement.

ABSOLUTE MAXIMUM RATINGS AT TA=25℃

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation	100	mW
Peak Forward Current (300pps, 10 μs pulse)	1	A
Continuous Forward Current	60	mA
Reverse Voltage	5	V
Operating Temperature Range	-40℃ to + 85℃	
Storage Temperature Range	-55℃ to + 100℃	
Lead Soldering Temperature [1.6mm(.063") From Body]	260℃ for 5 Seconds	

ELECTRICAL / OPTICAL CHARACTERISTICS AT TA=25℃

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	BIN NO.
Aperture Radiant Incidence	Ee	0.184		0.54	mW/cm^2	I_F = 20mA	BIN A
		0.36		0.78			BIN B
		0.52		1.02			BIN C
		0.68					BIN D
Radiant Intensity	I_E	1.383		4.06	mW/sr	I_F = 20mA	BIN A
		2.71		5.87			BIN B
		3.91		7.67			BIN C
		5.11					BIN D
Peak Emission Wavelength	λ_P		940		nm	I_F = 20mA	
Spectral Line Half-Width	$\Delta\lambda$		50		nm	I_F = 20mA	
Forward Voltage	V_F		1.2	1.6	V	I_F = 50mA	
Reverse Current	I_R			100	μA	V_R = 5V	
Viewing Angle (See FIG.6)	$2\theta_{1/2}$		60		deg.		

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25℃ Ambient Temperature Unless Otherwise Noted)

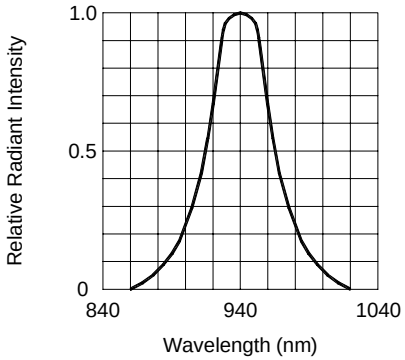


FIG.1 SPECTRAL DISTRIBUTION

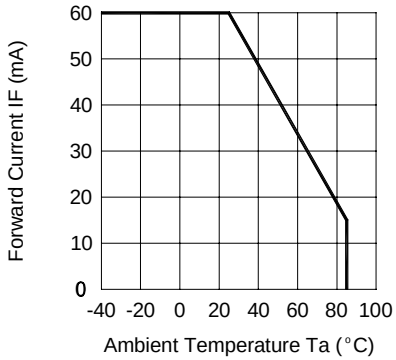


FIG.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

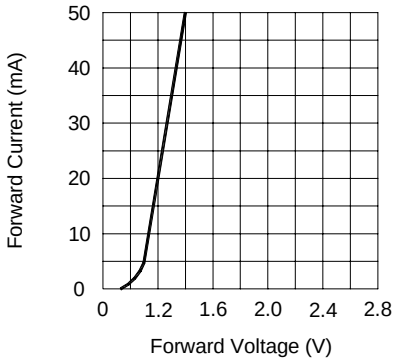


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

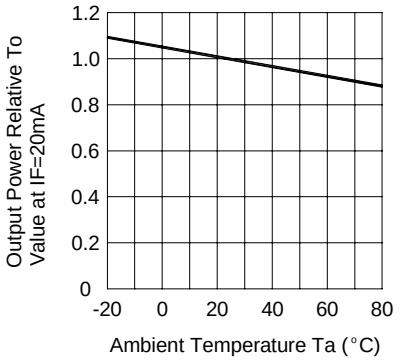


FIG.4 RELATIVE RADIANT INTENSITY VS. AMBIENT TEMPERATURE

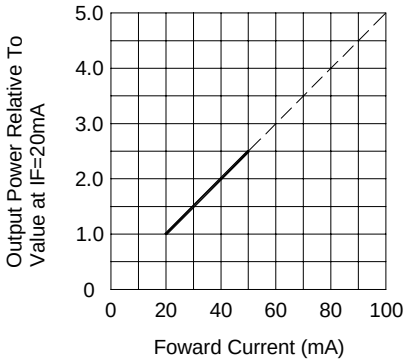


FIG.5 RELATIVE RADIANT INTENSITY VS. FORWARD CURRENT

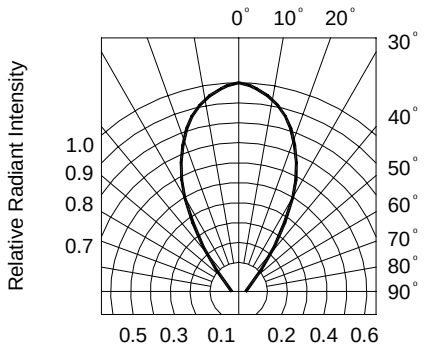


FIG.6 RADIATION DIAGRAM